ALLIANCE MEMORY MDS REPORT

Part Number:	**AS5F38G04SND-08LIN**								
Part Weight:	**78.04mg**								
No.	**Part Name**	**Material Name**	**Component wt (mg)**	**Material Content (Element)**	**CAS Number**	**Element wt (%)**	**Element wt (mg)**	**wt % of Total unit wt**	**PPM**
1	Substrate	HL-832NX-A / AUS 308	20.11	Copper (Cu)	7440-50-8	**11.02%**	**2.216**	**2.84%**	**110200**
				Nickel (Ni)	7440-02-0	**1.50%**	**0.302**	**0.39%**	**15000**
				Gold (Au)	7440-57-5	**0.25%**	**0.050**	**0.06%**	**2500**
				solder mask	Tradesecret	**16.25%**	**3.268**	**4.19%**	**162500**
				Cured thermosetting resin (including inorganic filler)	Trade Secret	**30.00%**	**6.033**	**7.73%**	**300000**
				Continuous Filament Fiber Glass	Trade Secret	**40.98%**	**8.241**	**10.56%**	**409800**
2	Mold compound	G760	49.126	2,2'-((3,3',5,5'-tetramethyl-(1,1'-biphenyl)-4,4'-diyl)bis(oxymethylene))-bis-oxirane	85954-11-6	**8.00%**	**3.930**	**5.04%**	**80000**
				Phenol Resin A	Trade Secret	**2.70%**	**1.326**	**1.70%**	**27000**
				Phenol Resin B	Trade Secret	**2.80%**	**1.376**	**1.76%**	**28000**
				Silica(Amorphous) A	60676-86-0	**70.00%**	**34.388**	**44.07%**	**700000**
				Silica(Amorphous) B	7631-86-9	**8.00%**	**3.930**	**5.04%**	**80000**
				Metal Hydroxide	Trade Secret	**8.00%**	**3.930**	**5.04%**	**80000**
				Carbon Black	1333-86-4	**0.50%**	**0.246**	**0.31%**	**5000**
3	DAF	EM760	1.413	Acrylic resin (Die attach film)	Trade Secret	**50.00%**	**0.706**	**0.91%**	**500000**
				Silica, amorphous(Die attach film)	7631-86-9	**45.00%**	**0.636**	**0.81%**	**450000**
				Phenol resin (Die attach film)	Trade Secret	**5.00%**	**0.071**	**0.09%**	**50000**
4	Gold wire	Au	0.219	Gold	7440-57-5	**100.00%**	**0.219**	**0.28%**	**999960**
				Calcium	7440-70-2	**0.00%**	**0.000**	**0.00%**	**40**
5	Die	Chip	7.172	Silicon	7440-21-3	**98.00%**	**7.028**	**9.01%**	**980000**
				Aluminum	7429-90-5	**2.00%**	**0.143**	**0.18%**	**20000**
			78.04			500.00%	78.040	100.00%	5000000